

C0805C200F1HACTU

Aliases (C0805C200F1HAC7800) SMD Comm X8R HT150C, Ceramic, 20 pF, 1%, 100 VDC, X8R, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.7 mm



General Information				
Series	SMD Comm X8R HT150C			
Style	SMD Chip			
Description	SMD, MLCC, High Temperature, Ultra-Stable			
Features	High Temperature, Ultra-Stable			
RoHS	Yes			
Termination	Tin			
Marking	No			
AEC-Q200	No			
Typical Component Weight	11 mg			
Shelf Life	78 Weeks			
MSL	1			

Dimensions		
Chip Size	0805	
L	2mm +/-0.2mm	
W	1.25mm +/-0.2mm	
Т	0.78mm +/-0.10mm	
S	0.7mm MIN	
В	0.5mm +/-0.25mm	

Т	0.78mm +/-0.10mm
S	0.7mm MIN
В	0.5mm +/-0.25mm
Packaging Specifications	

	Specifications	ations		
	Capacitance	20 pF		
	Measurement Condition	1 MHz 1.0Vrms		
	Tolerance	1%		
	Voltage DC	100 VDC		
	Dielectric Withstanding Voltage	250 VDC		
	Temperature Range	-55/+150°C		
	Temp. Coefficient	X8R		
	Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1MegaHz 1.0Vrms		
	Dissipation Factor	2.5% 1 MHz 1.0 Vrms		
	Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
	Insulation Resistance	100 GOhms		

Packaging Specifications		Capacitance Cha
Packaging	T&R, 180mm, Paper Tape	Reference to +25 Applied (TCC)
Packaging Quantity	4000	Dissipation Facto
		2.00.pat.o aoto

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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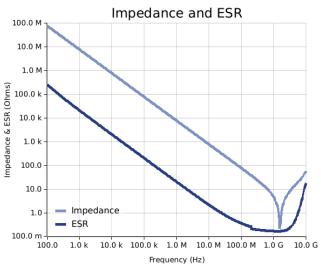


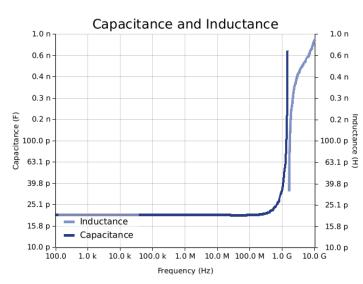
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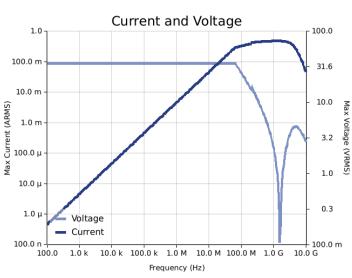
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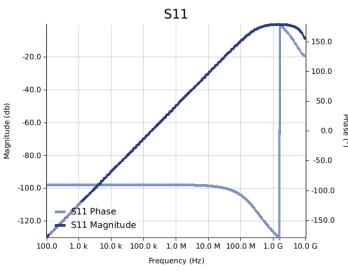
Simulations

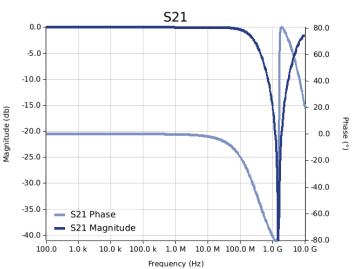
For the complete simulation environment please visit K-SIM.











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These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for ripple Ripple Currenty votage vs. rrequency plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
 The effects shown herein are based on measured data from a multiple part sample of the parts in question.
 Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
 The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages
- generated at any other harmonics.

 Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

All Information given herein is believed to be accurate and reliable, but is presented without guarantee, warranty, or responsibility of any kind, expressed or implied. Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute – and we specifically disclaim – any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

If you have any questions please contact K-SIM.

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